

BUK9524-55A

N-channel TrenchMOS logic level FET

Rev. 02 — 27 January 2011 Product data sheet

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- AEC Q101 compliant
- Low conduction losses due to low on-state resistance
- Suitable for logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V and 24 V loads
- Automotive and general purpose power switching
- Motors, lamps and solenoids

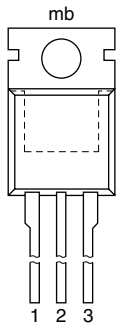
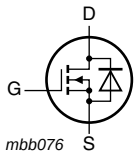
1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C	-	-	55	V
I_D	drain current	V_{GS} = 5 V; T_{mb} = 25 °C; see Figure 1; see Figure 3	-	-	46	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2	-	-	105	W
Static characteristics						
R_{DSon}	drain-source on-state resistance	V_{GS} = 4.5 V; I_D = 25 A; T_j = 25 °C	-	-	26	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C	-	19	21.7	mΩ
		V_{GS} = 5 V; I_D = 25 A; T_j = 25 °C; see Figure 12; see Figure 13	-	20	24	mΩ
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	I_D = 46 A; $V_{sup} \leq 25$ V; R_{GS} = 50 Ω; V_{GS} = 5 V; $T_{j(init)}$ = 25 °C; unclamped	-	-	76	mJ

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	drain		
3	S	source		
mb	D	mounting base; connected to drain		

SOT78A (TO-220AB)

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9524-55A	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78A

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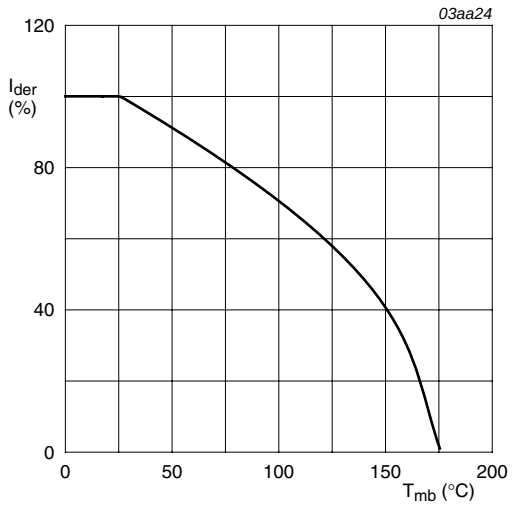
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4. Limiting values

Table 4. Limiting values

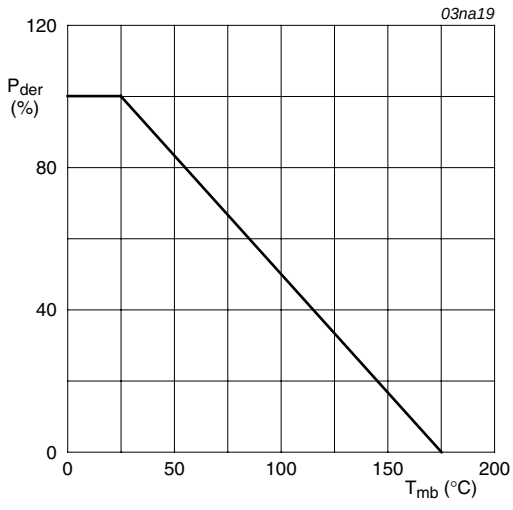
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C	-	55	V
V_{DGR}	drain-gate voltage	R_{GS} = 20 kΩ	-	55	V
V_{GS}	gate-source voltage		-10	10	V
I_D	drain current	T_{mb} = 25 °C; V_{GS} = 5 V; see Figure 1; see Figure 3	-	46	A
		T_{mb} = 100 °C; V_{GS} = 5 V; see Figure 1	-	33	A
I_{DM}	peak drain current	T_{mb} = 25 °C; pulsed; $t_p \leq 10$ µs; see Figure 3	-	188	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2	-	105	W
T_{stg}	storage temperature		-55	175	°C
T_j	junction temperature		-55	175	°C
V_{GSM}	peak gate-source voltage	pulsed; $t_p \leq 50$ µs	-15	15	V
Source-drain diode					
I_S	source current	T_{mb} = 25 °C	-	46	A
I_{SM}	peak source current	pulsed; $t_p \leq 10$ µs; T_{mb} = 25 °C	-	188	A
Avalanche ruggedness					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	I_D = 46 A; $V_{sup} \leq 25$ V; R_{GS} = 50 Ω; V_{GS} = 5 V; $T_{j(init)}$ = 25 °C; unclamped	-	76	mJ



$$I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\,\%$$

Fig 1. Normalized continuous drain current as a function of mounting base temperature

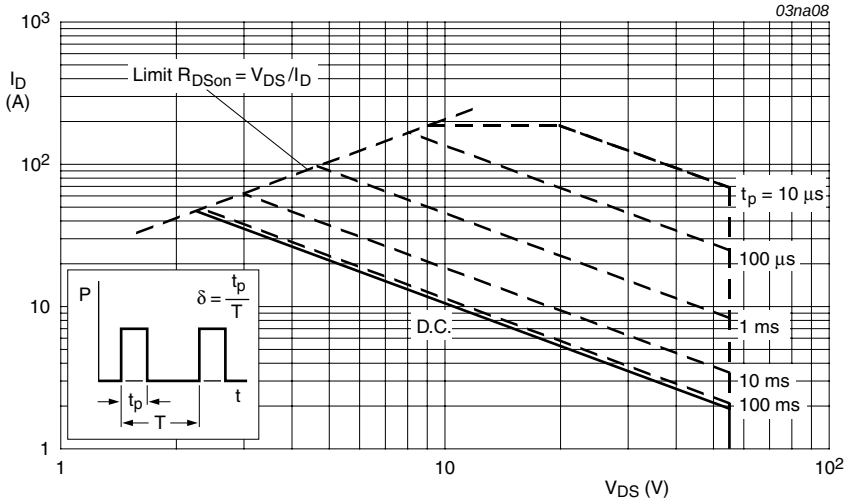


$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\,\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature

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$T_{mb} = 25°C; I_{DM}$ is single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

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5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base		-	-	1.4	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	vertical in still air ; lead length ≤ 5 mm ; see Figure 4	-	60	-	K/W

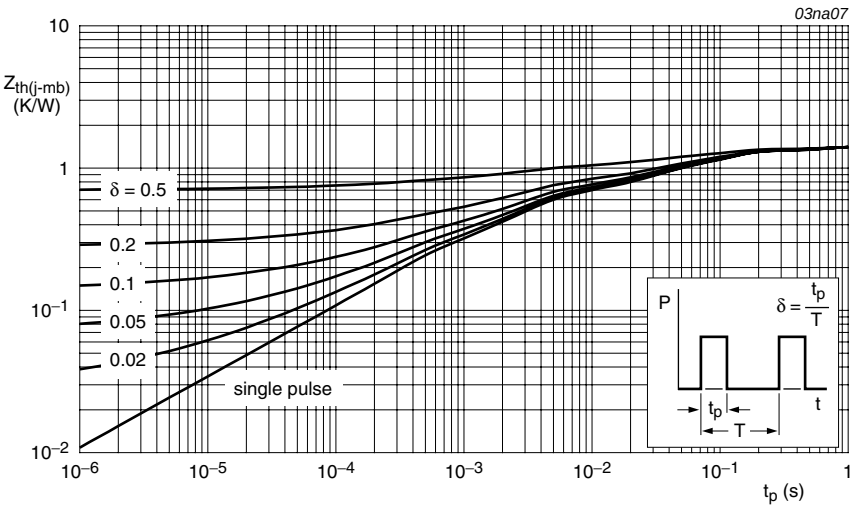


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

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6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 0.25 mA; V_{GS} = 0 V; T_j = -55 °C	50	-	-	V
		I_D = 0.25 mA; V_{GS} = 0 V; T_j = 25 °C	55	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C; see Figure 11	1	1.5	2	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 175 °C; see Figure 11	0.5	-	-	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C; see Figure 11	-	-	2.3	V
I_{DSS}	drain leakage current	V_{DS} = 55 V; V_{GS} = 0 V; T_j = 25 °C	-	0.05	10	µA
		V_{DS} = 55 V; V_{GS} = 0 V; T_j = 175 °C	-	-	500	µA
I_{GSS}	gate leakage current	V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25 °C	-	2	100	nA
		V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25 °C	-	2	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 5 V; I_D = 25 A; T_j = 175 °C; see Figure 12; see Figure 13	-	-	50	mΩ
		V_{GS} = 4.5 V; I_D = 25 A; T_j = 25 °C	-	-	26	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C	-	19	21.7	mΩ
		V_{GS} = 5 V; I_D = 25 A; T_j = 25 °C; see Figure 12; see Figure 13	-	20	24	mΩ
Dynamic characteristics						
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz; T_j = 25 °C; see Figure 8	-	1361	1815	pF
C_{oss}	output capacitance		-	239	287	pF
C_{rss}	reverse transfer capacitance		-	162	222	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 30 V; R_L = 1.2 Ω; V_{GS} = 5 V; $R_{G(ext)}$ = 10 Ω; T_j = 25 °C	-	17.5	-	ns
t_r	rise time		-	104	-	ns
$t_{d(off)}$	turn-off delay time		-	82.5	-	ns
t_f	fall time		-	80	-	ns
L_D	internal drain inductance	from contact screw on mounting base to centre of die ; T_j = 25 °C	-	3.5	-	nH
		from drain lead 6 mm from package to centre of die ; T_j = 25 °C	-	4.5	-	nH
L_S	internal source inductance	from source lead to source bond pad ; T_j = 25 °C	-	7.5	-	nH
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 25 A; V_{GS} = 0 V; T_j = 25 °C; see Figure 14	-	0.85	1.2	V
t_{rr}	reverse recovery time	I_S = 46 A; dI_S/dt = -100 A/µs; V_{GS} = -10 V; V_{DS} = 30 V; T_j = 25 °C	-	50	-	ns
Q_r	recovered charge		-	85	-	nC

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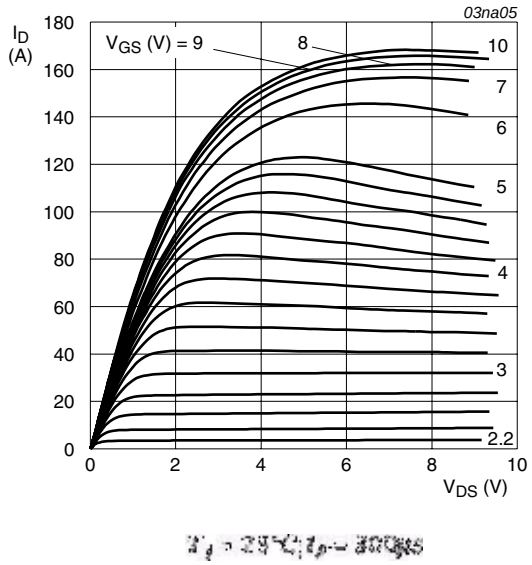


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

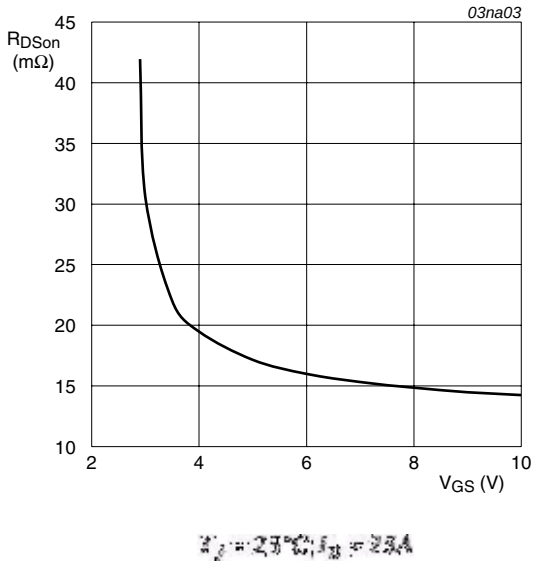


Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values

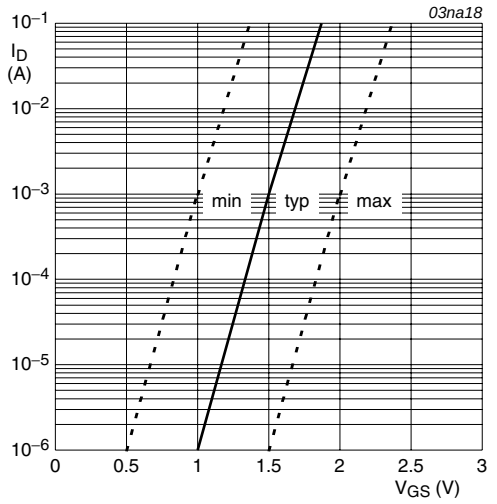


Fig 7. Sub-threshold drain current as a function of gate-source voltage

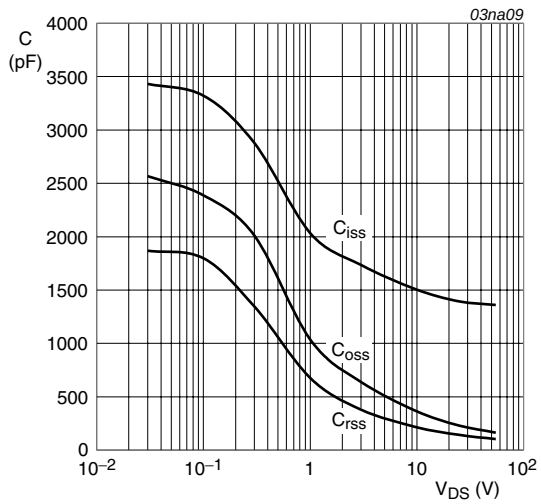


Fig 8. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

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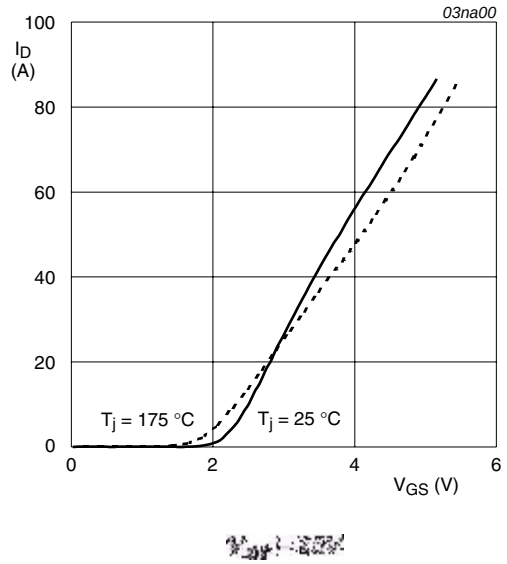


Fig 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

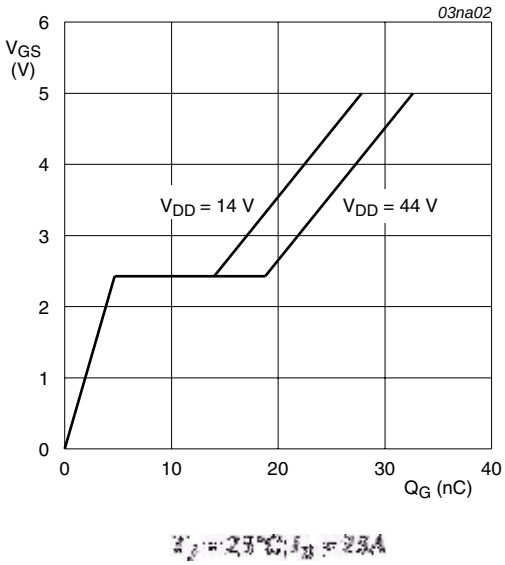


Fig 10. Gate-source voltage as a function of gate charge; typical values

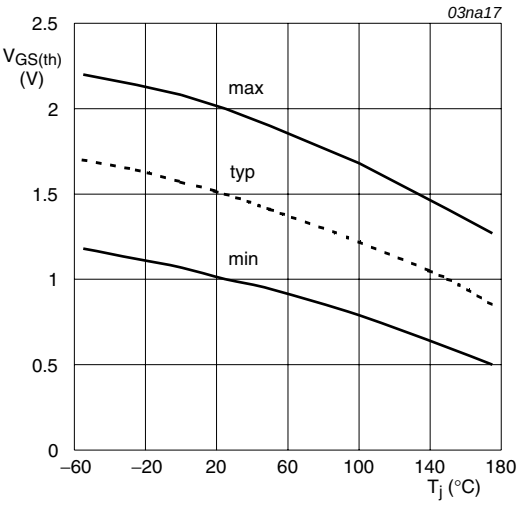


Fig 11. Gate-source threshold voltage as a function of junction temperature

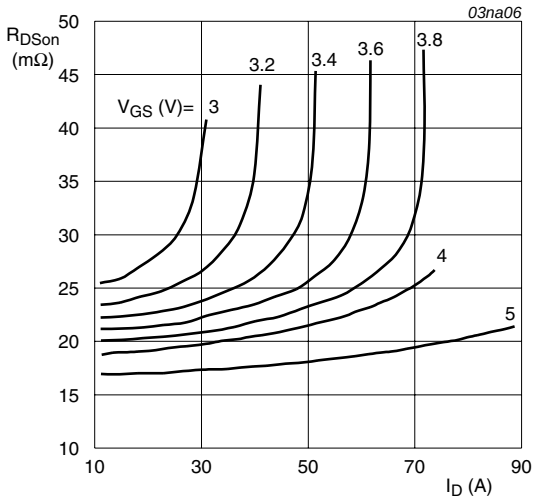
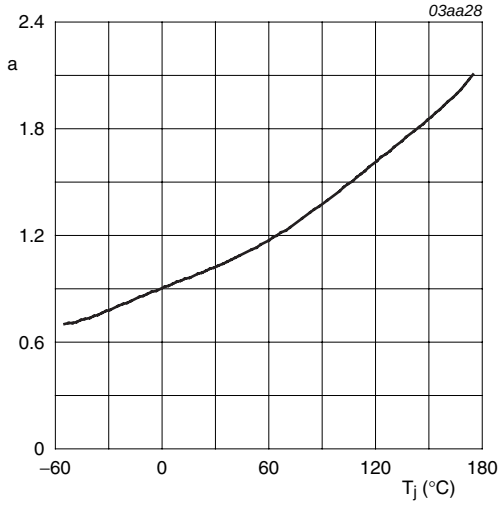


Fig 12. Drain-source on-state resistance as a function of drain current; typical values

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$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature

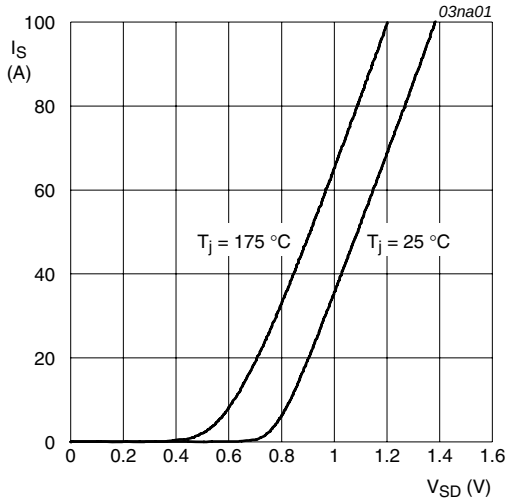


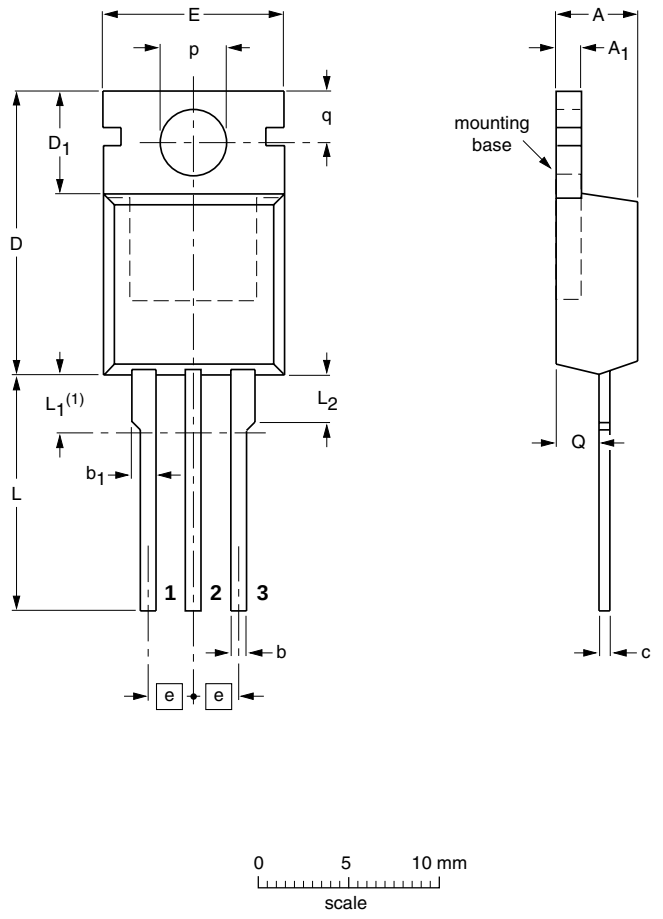
Fig 14. Reverse diode current as a function of reverse diode voltage; typical values

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7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB **SOT78A**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	b_1	c	D	D_1	E	e	L	L_1(1)	L_2 max.	p	q	Q
mm	4.5 4.1	1.39 1.27	0.9 0.6	1.3 1.0	0.7 0.4	15.8 15.2	6.4 5.9	10.3 9.7	2.54	15.0 13.5	3.30 2.79	3.0	3.8 3.6	3.0 2.7	2.6 2.2

Note

1. Terminals in this zone are not tinned.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78A		3-lead TO-220AB	SC-46			~~03-01-22~~ 05-03-14

Fig 15. Package outline SOT78A (TO-220AB)

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8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK9524-55A v.2	20110127	Product data sheet	-	BUK9524_9624_55A v.1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Type number BUK9524-55A separated from data sheet BUK9524_9624_55A v.1.			
BUK9524_9624_55A v.1	20000929	Product specification	-	-

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9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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